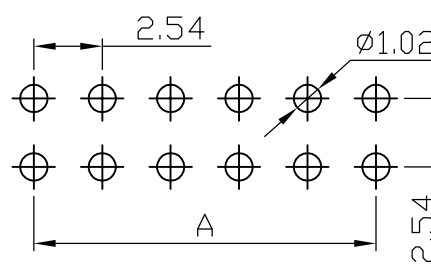
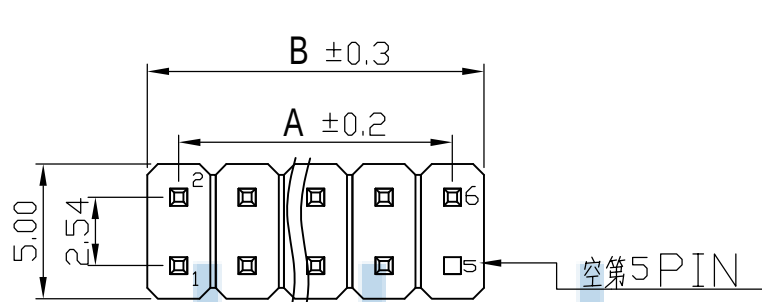
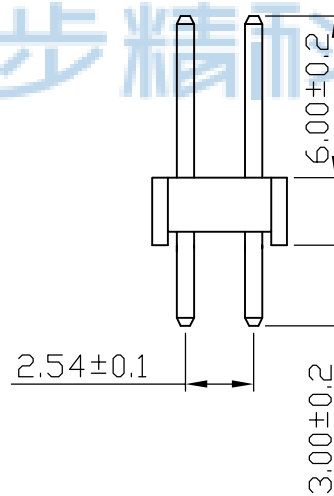
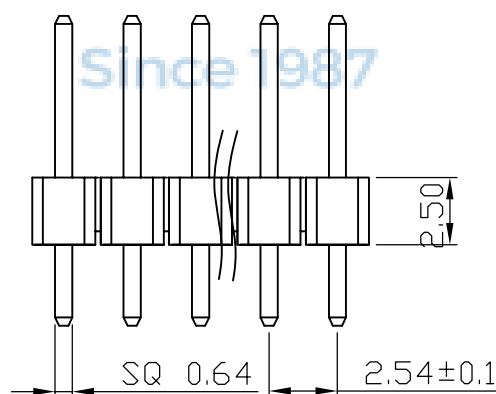


6		7		8	
REV.	ECN NO.	CONTENT	DATE	ENGINEER	
A0					



RECOMMEND P. C. B LAYOUT

PCB TOLERANCE: ± 0.05 (TOP VIEW)



SPECIFICATIONS

Current Rating: 3Amps
Insulation Resistance: 1000M Ω Min
Contact Resistance: 20M Ω Max
Withstanding Voltage: AC 1000V
Operation Temperature: -40° to +105°
Contact Material: Copper Alloy
Standard: PA6T
Insulator Material: Polyester (UL 94V-0)
Contact Plating: Gold Flash
Max. Processing Temp: 240° C for 30-60 seconds
(260° C for 5 seconds)

No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B
1	0.00	2.54	11	25.40	27.94	21	50.80	53.34	31	76.20	78.74
2	2.54	5.08	12	27.94	30.48	22	53.34	55.88	32	78.74	81.28
3	5.08	7.62	13	30.48	33.02	23	55.88	58.42	33	81.28	83.82
4	7.62	10.16	14	33.02	35.56	24	58.42	60.96	34	83.82	86.36
5	10.16	12.70	15	35.56	38.10	25	60.96	63.50	35	86.36	88.90
6	12.70	15.24	16	38.10	40.64	26	63.50	66.04	36	88.90	91.44
7	15.24	17.78	17	40.64	43.18	27	66.04	68.58	37	91.44	93.98
8	17.78	20.32	18	43.18	45.72	28	68.58	71.12	38	93.98	96.52
9	20.32	22.86	19	45.72	48.26	29	71.12	73.66	39	96.52	99.06
10	22.86	25.40	20	48.26	50.80	30	73.66	76.20	40	99.06	101.60

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PDWG,NO: 0266-1

 深圳市步步精科技有限公司			
.X: ± 0.38 .XX: ± 0.25 .XXX: ± 0.13		X*: $\pm 3^*$.X*: $\pm 2^*$.XX*: $\pm 1^*$	
APPD. JM_Zheng		NAME: 排针 2.54PH H2.5 2x3P 180度 PC3.0 PA6.0 PB2.5 L11.5 6T 空第5P 常规 袋装	
CHKD. LYX		 PJ. NO.: PH.05.12-41-6038	SIZE: A4 DRW NO.:
DR. LHC		FINISH: SEE NOTES	MAT'L.: SEE NOTES
		SCALE: N/A	REV.: A3 UNIT: mm PAGE: 1/1